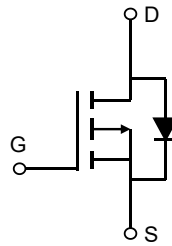


Description

Features

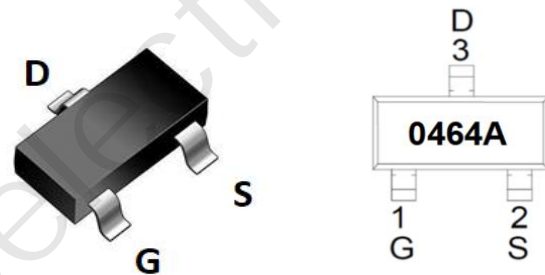
- -40V, -3A
 $R_{DS(ON)}$ Typ = 65mΩ @ $V_{GS} = -10V$
 $R_{DS(ON)}$ Typ = 85mΩ @ $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

| Device | Marking | Package | Outline | Reel Size | Reel (pcs) | Per Carton (pcs) |
|-------------|---------|---------|---------|-----------|------------|------------------|
| CRMLBL0464A | 0464A | SOT-23 | TAPING | 7" | 3000 | 120000 |

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Value | Units |
|-----------------|--|---------------------------|-------|
| V_{DS} | Drain-to-Source Voltage | -40 | V |
| V_{GS} | Gate-to-Source Voltage | ±20 | V |
| I_D | Continuous Drain Current | $T_A = 25^\circ\text{C}$ | -3 |
| | | $T_A = 100^\circ\text{C}$ | -1.8 |
| I_{DM} | Pulsed Drain Current ⁽¹⁾ | -12 | A |
| P_D | Power Dissipation | $T_A = 25^\circ\text{C}$ | 1.32 |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient ⁽²⁾ | 95 | °C/W |
| T_J, T_{STG} | Junction & Storage Temperature Range | -55 to 150 | °C |

Electrical Characteristics (T_J = 25°C unless otherwise specified)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|--|---|------|------|------|------|
| Off Characteristics | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | I _D = -250μA, V _{GS} = 0V | -40 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = -40V, V _{GS} = 0V | - | - | -1.0 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{DS} = 0V, V _{GS} = ±20V | - | - | ±100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = -250μA | -1.1 | -1.6 | -2.2 | V |
| R _{DS(ON)} | Static Drain-Source ON-Resistance ⁽³⁾ | V _{GS} = -10V, I _D = -1.2A | - | 65 | 85 | mΩ |
| | | V _{GS} = -4.5V, I _D = -1A | - | 85 | 111 | mΩ |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{GS} = 0V, V _{DS} = -20V, f = 1MHz | - | 316 | - | pF |
| C _{oss} | Output Capacitance | | - | 37 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 31 | - | pF |
| Q _g | Total Gate Charge | V _{GS} = 0 to -10V V _{DS} = -20V, I _D = -1.2A | - | 8 | - | nC |
| Q _{gs} | Gate Source Charge | | - | 1.5 | - | nC |
| Q _{gd} | Gate Drain("Miller") Charge | | - | 1.7 | - | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-On DelayTime | V _{GS} = -10V, V _{DD} = -20V I _D = -1.2A, R _{GEN} = 6Ω | - | 6 | - | ns |
| t _r | Turn-On Rise Time | | - | 5 | - | ns |
| t _{d(off)} | Turn-Off DelayTime | | - | 26 | - | ns |
| t _f | Turn-Off Fall Time | | - | 15 | - | ns |
| Drain-Source Diode Characteristics and Max Ratings | | | | | | |
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | -3 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | -12 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} = 0V, I _S = -1.5A | - | - | -1.2 | V |
| trr | Body Diode Reverse Recovery Time | I _F = -3A, di/dt = 100A/us | - | 20 | - | ns |
| Qrr | Body Diode Reverse Recovery Charge | | - | 12 | - | nC |

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. R_{θJA} is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

Test Circuit

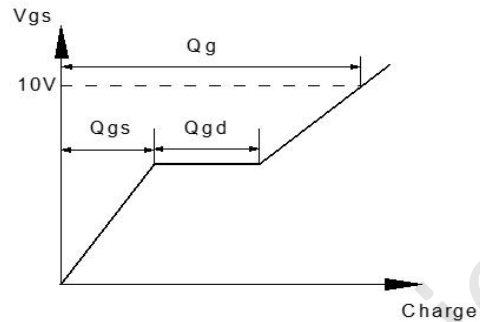
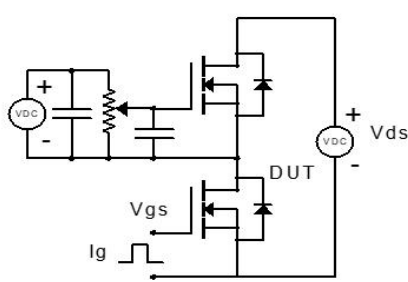


Figure 1: Gate Charge Test Circuit & Waveform

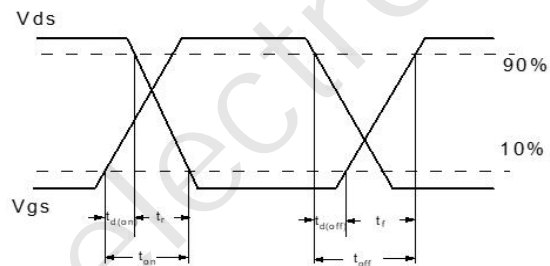
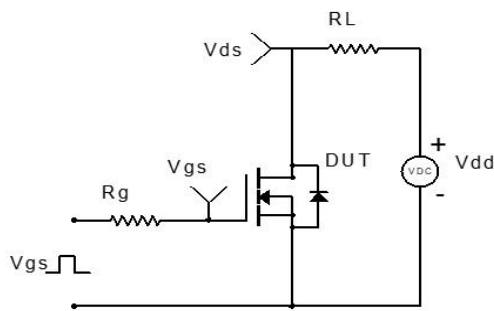


Figure 2: Resistive Switching Test Circuit & Waveform

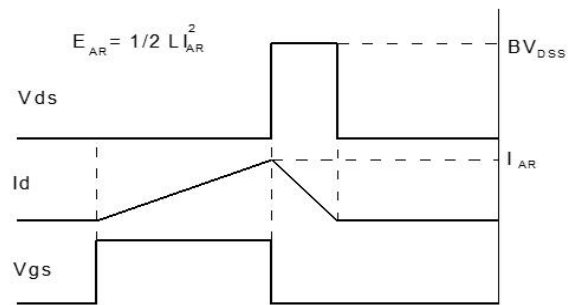
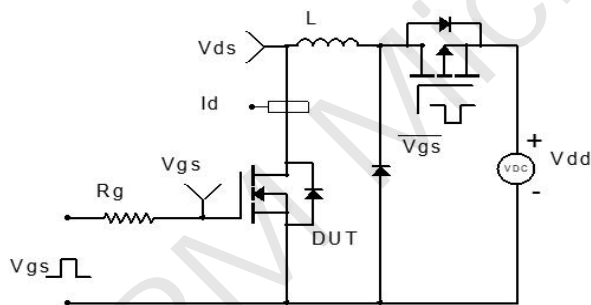


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

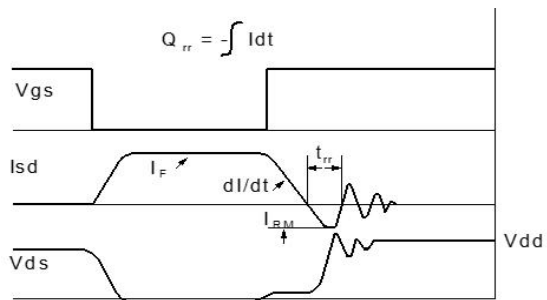
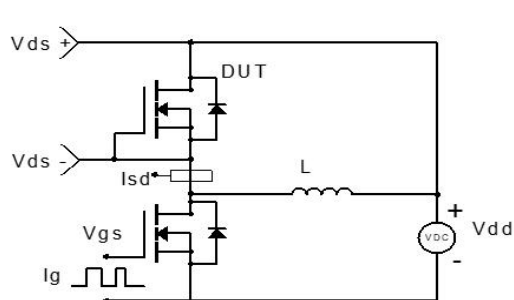
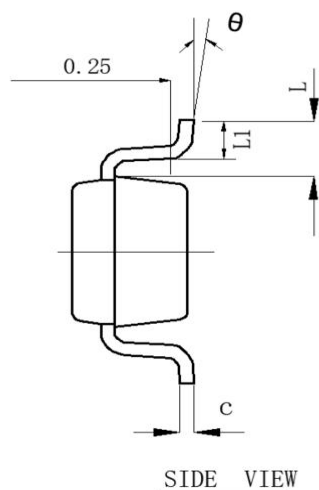
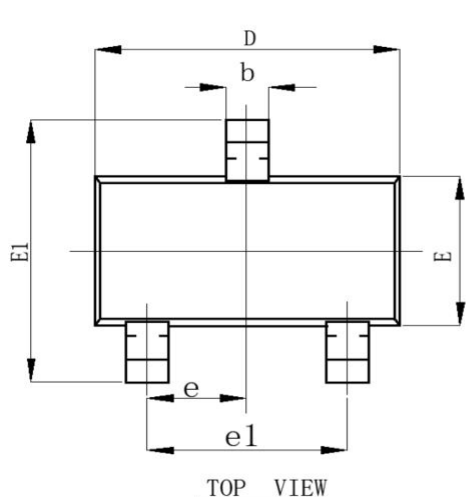
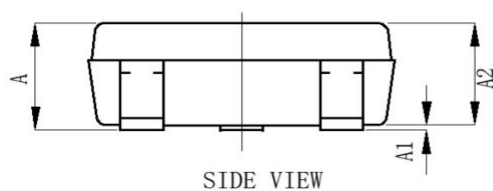


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-23)



| COMMON DIMENSIONS In Millimeters | | |
|----------------------------------|------------|-------|
| SYMBOL | MIN | MAX |
| A | 0.900 | 1.150 |
| A1 | 0.000 | 0.100 |
| A2 | 0.900 | 1.050 |
| b | 0.300 | 0.500 |
| c | 0.080 | 0.150 |
| D | 2.800 | 3.000 |
| E | 1.200 | 1.400 |
| E1 | 2.250 | 2.550 |
| L | 0.550 REF. | |
| θ | 0° | 8° |
| L1 | 0.300 | 0.500 |
| e | 0.950 TYP. | |
| e1 | 1.800 | 2.000 |




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